

# GalnAs 4th Junction for Next-Generation Lattice-Mismatched Multijunction Solar Cells

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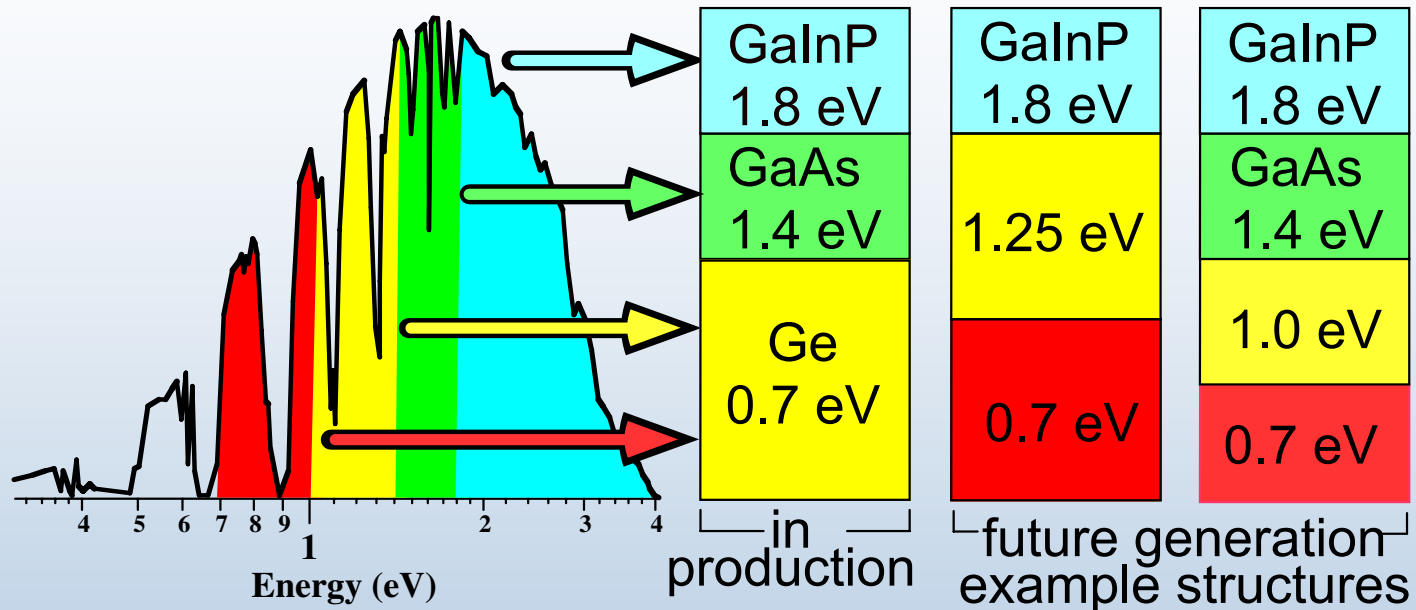
# The Fine Print

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# Evolution of Multijunction Devices

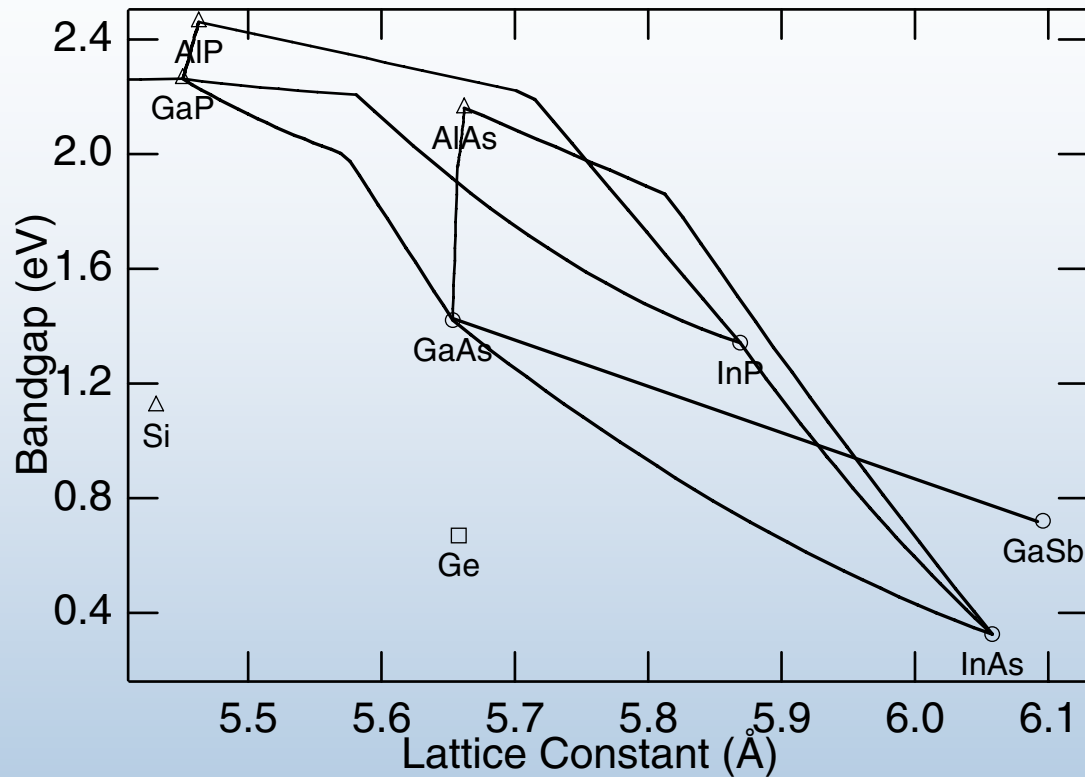


- Need to make better use of spectrum, esp. in 0.7–1.4 eV range
- How to do this...?

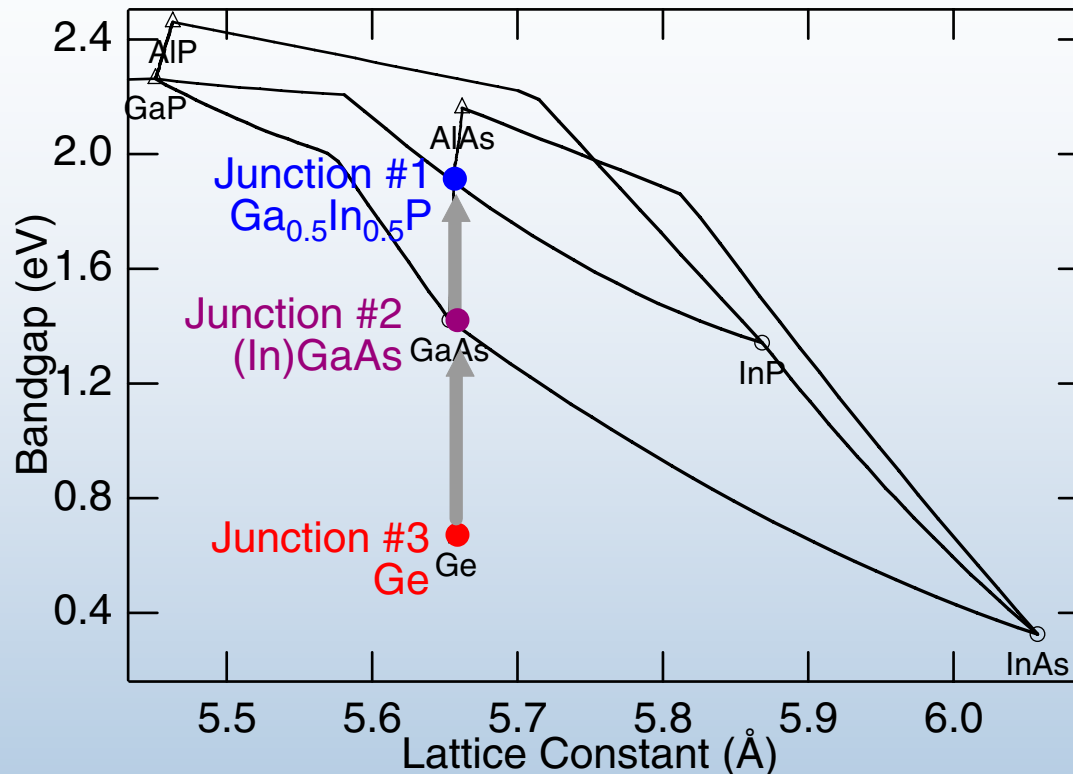
# Outline

- Approaches to next-generation high efficiencies: survey of the field
- The inverted mismatched 3-junction cell
- Adding a 4th junction
- Fabrication and testing of 4th junction
- How low a bandgap do we really need?
- Outlook

# Our Palette: the III-V Alloys



# Lattice-Matched to Ge (and GaAs)



Device structure:

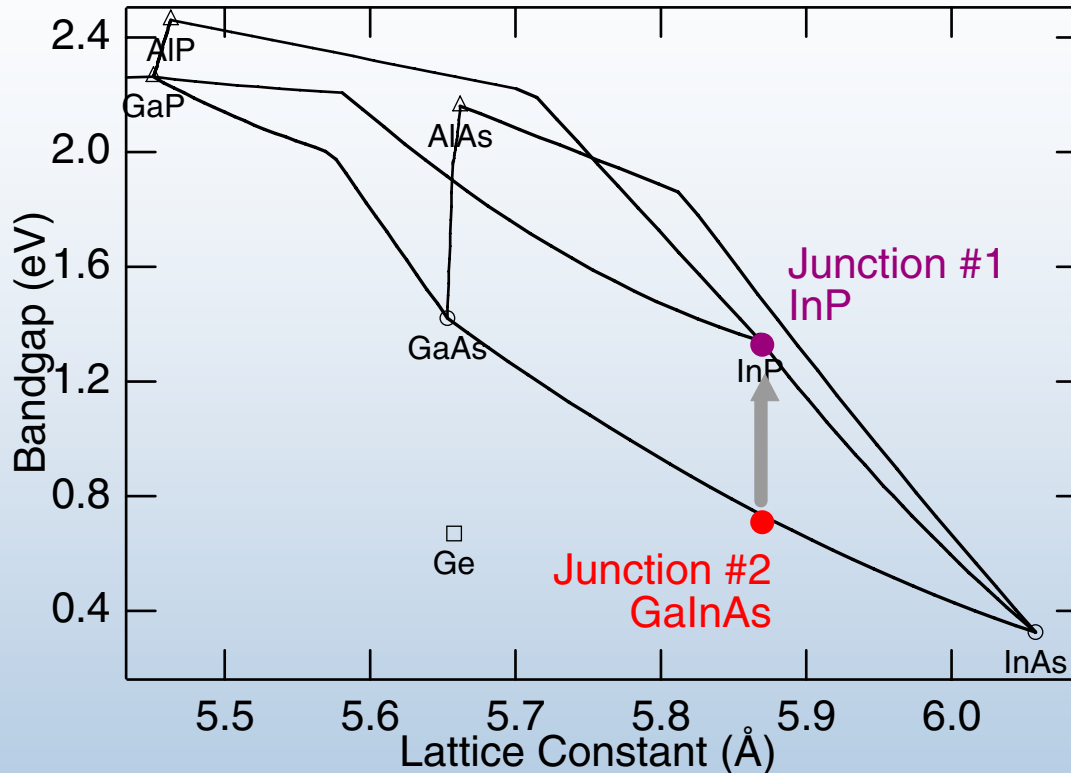


39%<sub>@236x</sub> by Spectrolab<sup>1</sup>

<sup>1</sup> King et al, 20th Eur. Solar Energy Conf. 2005 p.118

- The “standard” 3-junction device structure
  - Lattice-matched: easy to grow good material... but
  - Restricts available bandgap range

# Lattice-Matched to InP



Device structure:

Junction #1

Junction #2

31.8% @ 50x  
(three-terminal)  
by NREL<sup>1</sup>

<sup>1</sup> Wanlass et al, 21st PVSC,  
1990, p.38

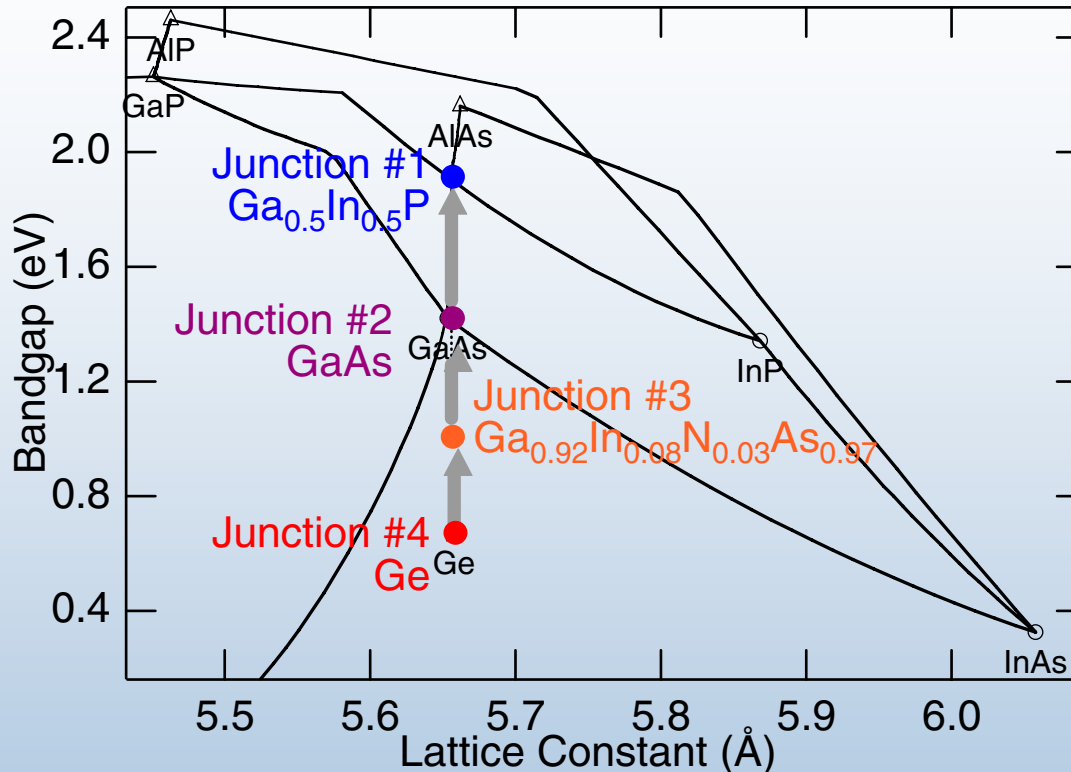
- Another example - lattice matching to InP

# Expanding our Range of Bandgap Options

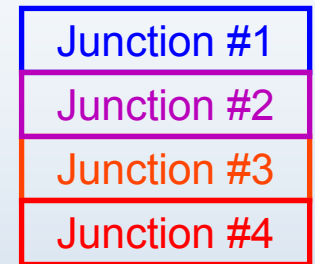
- New materials lattice-matched to GaAs: e.g. GaInNAs
  - Need good PV materials
- Junctions grown separately, then stacked
  - Mechanical stacking
  - Wafer bonding
- Lattice-mismatched epitaxy



# New Semiconductor: GaInNAs



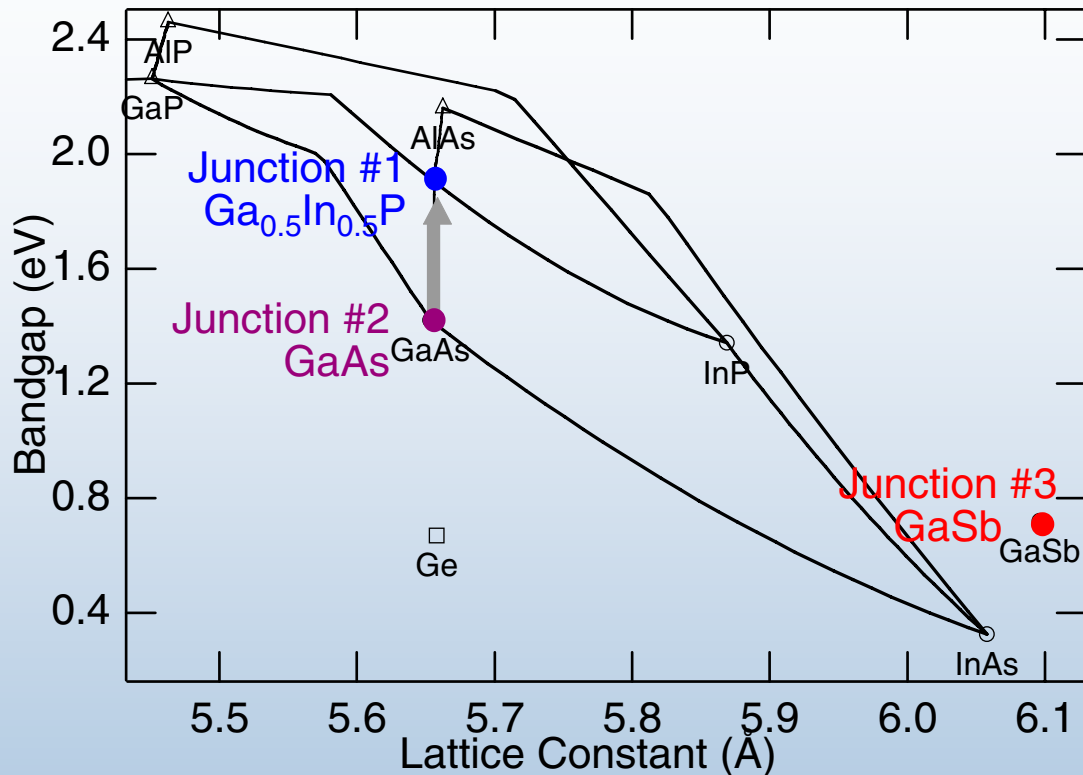
Device structure:



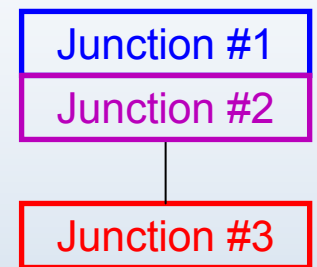
- <sup>1</sup> Ptak et al, 31st PVSC 2005, p. 603
- <sup>2</sup> Jackrel et al, this meeting
- <sup>3</sup> Meusel et al, 19th Eur.PVSEC 2004 p.3587
- <sup>4</sup> King et al, 19th Eur.PVSEC 2004 p.3581

- GaInNAs: lattice-matched, desired bandgap...
- But: short diffusion lengths >> poor device performance
- MBE may help growth<sup>1,2</sup>
- 5- or 6-junction structures may work around problems<sup>3,4</sup>

# Mechanically Stacked Junctions



Device structure:

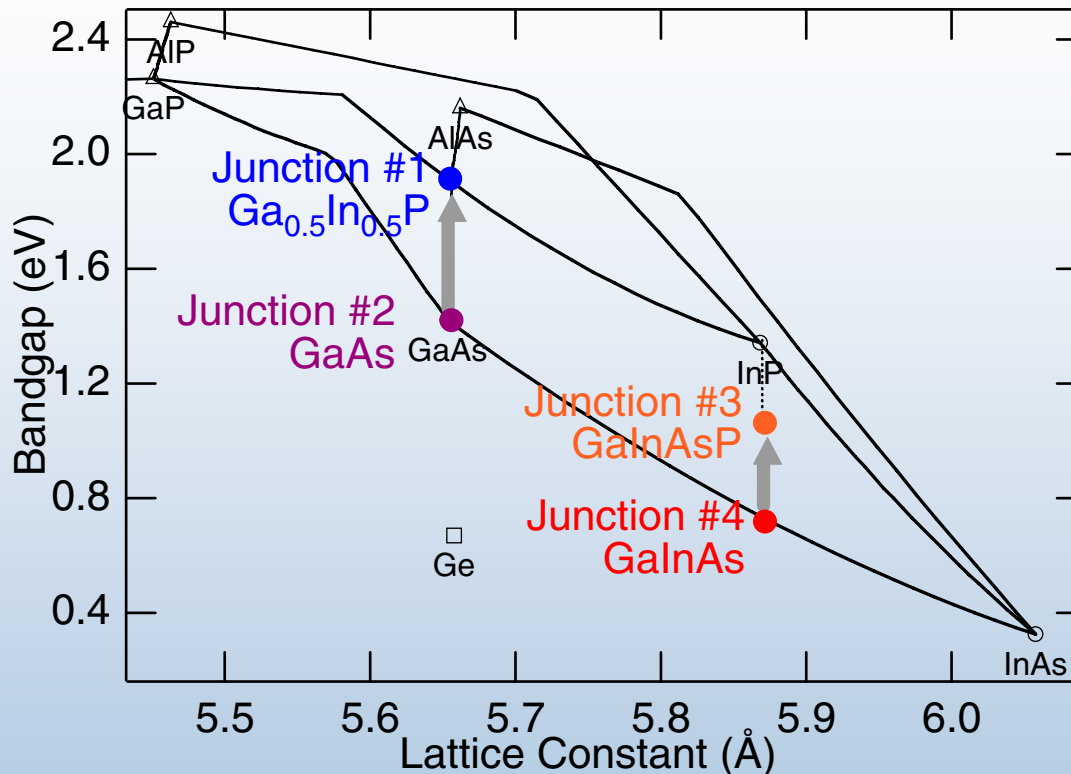


Fraas,<sup>1,2</sup>  
 Fraunhofer ISE  
 (33.5%<sub>@308x</sub>)<sup>3</sup>

- Extremely wide range of materials/bandgaps accessible: high efficiencies; e.g. 32.6% for GaAs/GaSb back in 1990<sup>1</sup>
- Not a single chip; multiple growths required

<sup>1</sup> Fraas et al, 21st PVSC 1990, p. 190  
<sup>2</sup> Fraas et al, 31st PVSC 2005, p. 751  
<sup>3</sup> Bett et al, 17th Eur. Solar Energy Conf. 2001 p.84

# Wafer-bonded Stacked Junctions



Device structure:

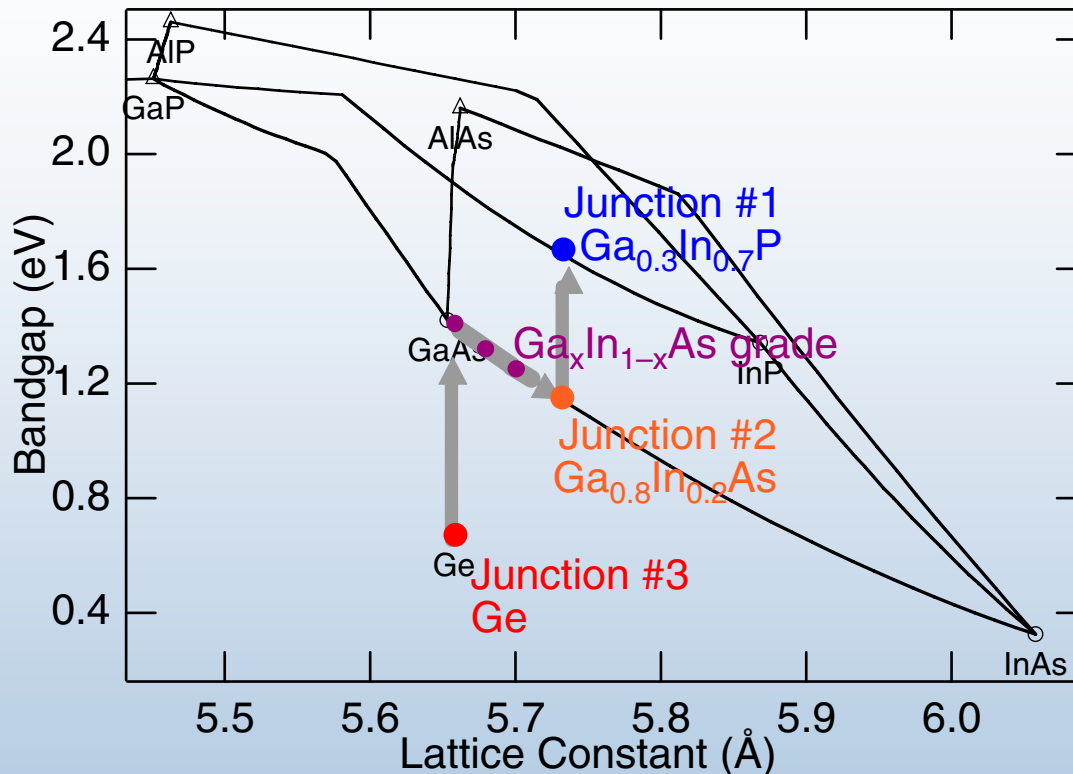


Atwater et al<sup>1</sup>

<sup>1</sup> Zahler et al, 29th PVSC 2002, p. 1039

- Wide range of materials/bandgaps accessible
- single chip / III-V integration with Si
- Multiple growths required; requires transparent conductive bond

# Lattice-mismatched (“metamorphic”) 3J



Device structure:



Spectrolab<sup>1</sup>,  
Fraunhofer ISE<sup>2</sup>  
EMCore<sup>3</sup>

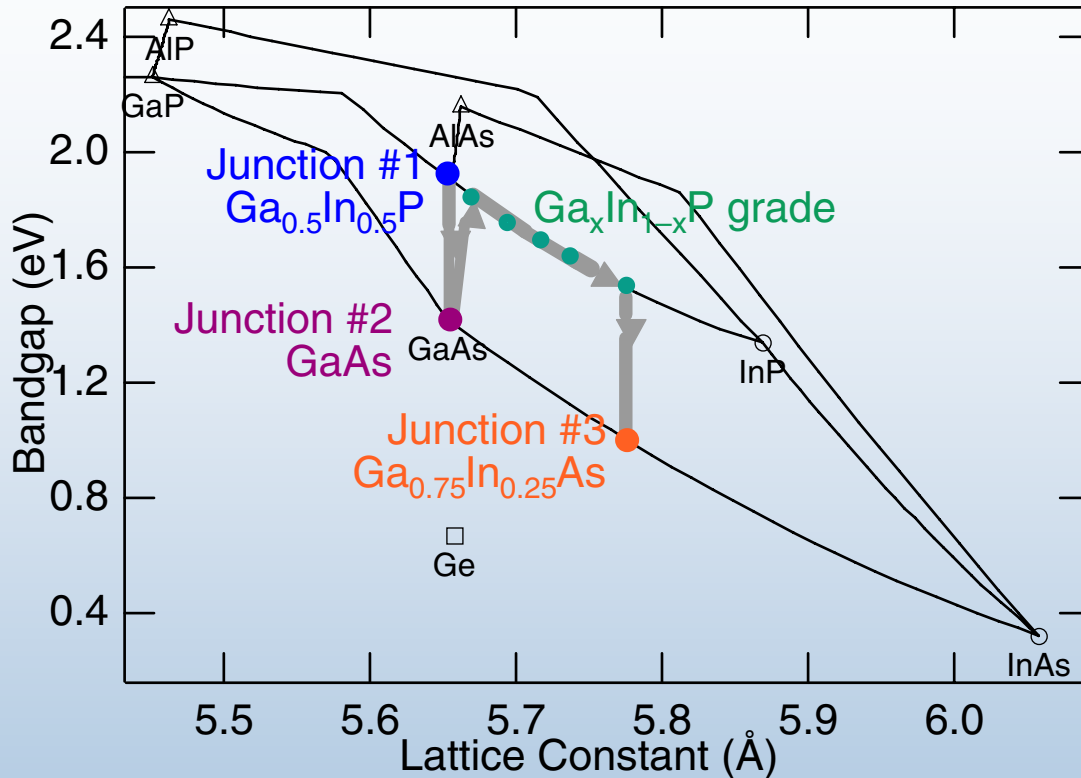
<sup>1</sup> Law et al, 31st PVSC, 2005, p.575

<sup>2</sup> Dimroth et al, Prog. Photovolt. **9**, 2005, p.165

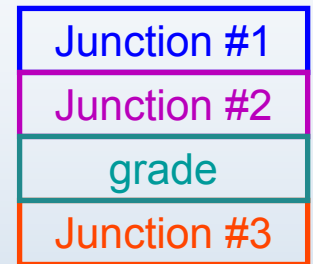
<sup>3</sup> Stan et al, 31st PVSC, 2005, p. 770

- Promising approach, competitive with lattice-matched
- Challenge is to maintain materials quality of junctions grown after grade

# Inverted Lattice-Mismatched Structure



Device structure:



Wanlass et al<sup>1,2</sup>

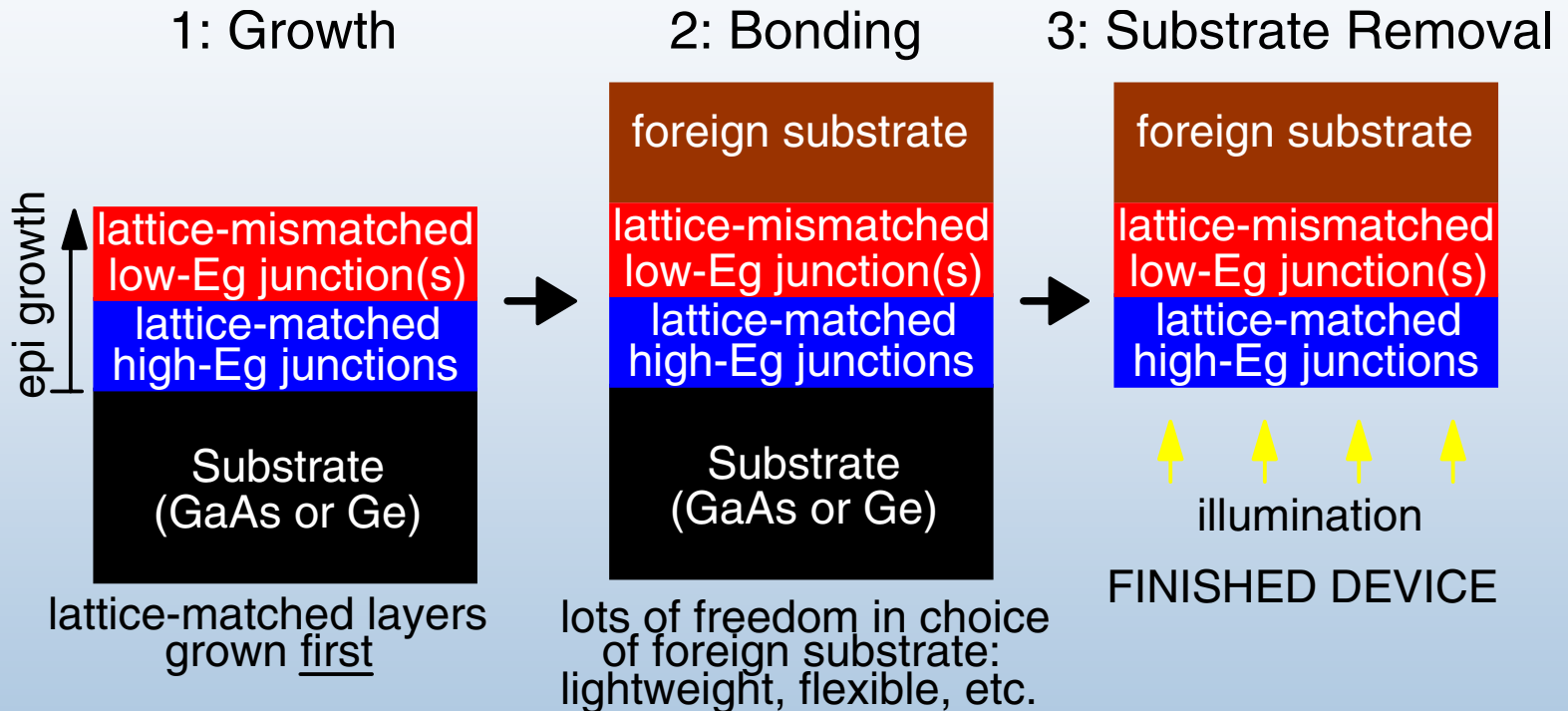
<sup>1</sup> Wanlass et al, 31st PVSC 2005, p. 530

<sup>2</sup> Wanlass et al, this meeting

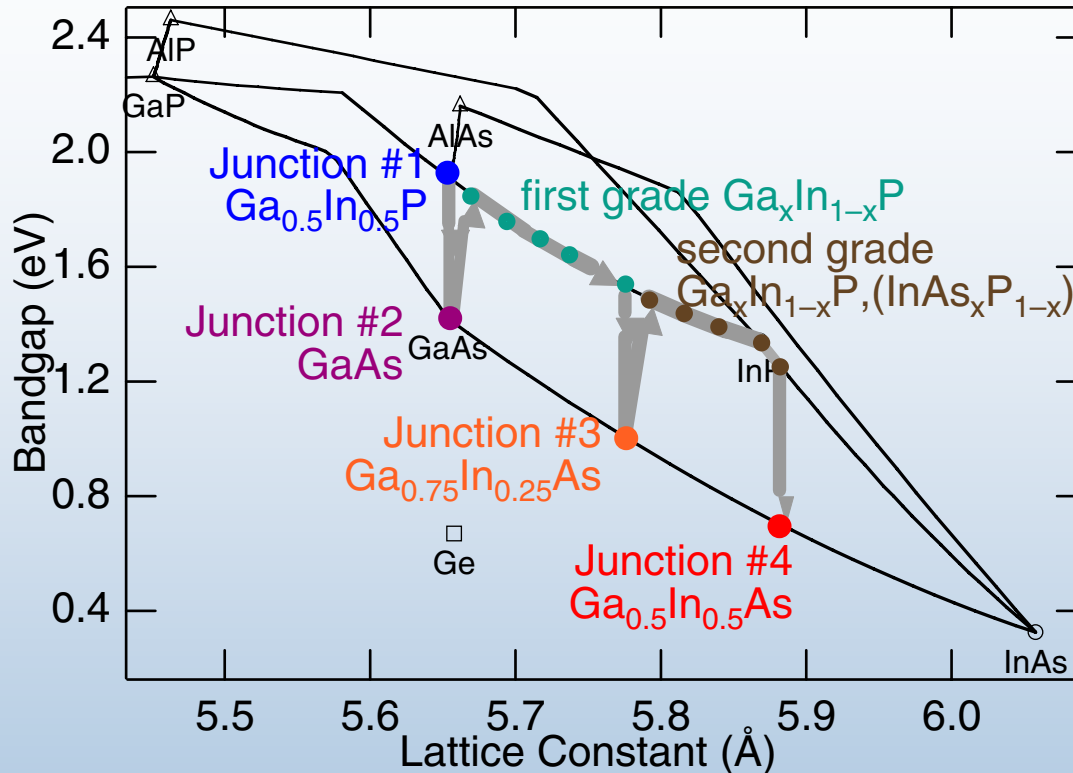
<sup>3</sup> Schultz et al, 21st PVSC 1990, p. 148

- Only the bottom junction is grown mismatched
  - Similar philosophy to Varian GaInP/GaAs/substrate/GaInAs design<sup>3</sup>
- Potential for very high efficiencies (38% achieved w.o. optimization)
- Some complexities but also opportunities in the processing...

# Processing of Inverted Structure



# Inverted LMM: Adding a 4th Junction



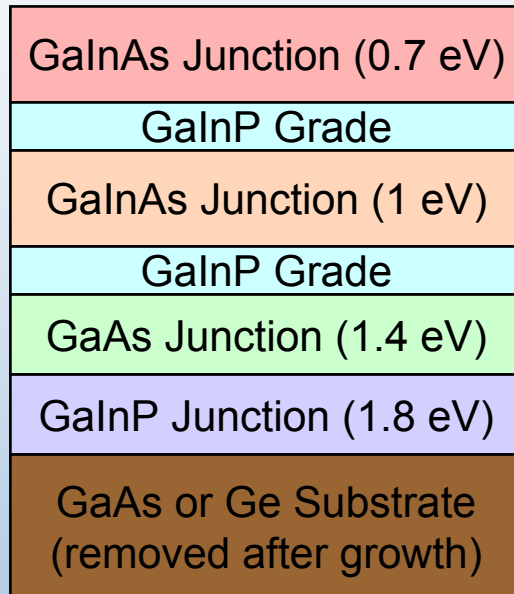
Device structure:



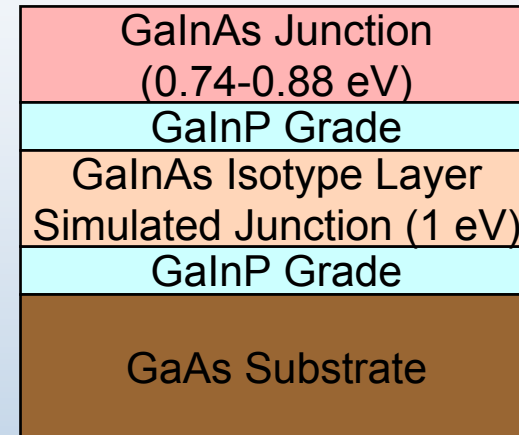
- Extend advantages of inverted 3-junction structure to higher efficiencies
- But: how far can we grade? How far do we need to grade?

# 4th Junction: Test Structure

Inverted 4 Junction  
Design:



4th Junction  
Test Structure:

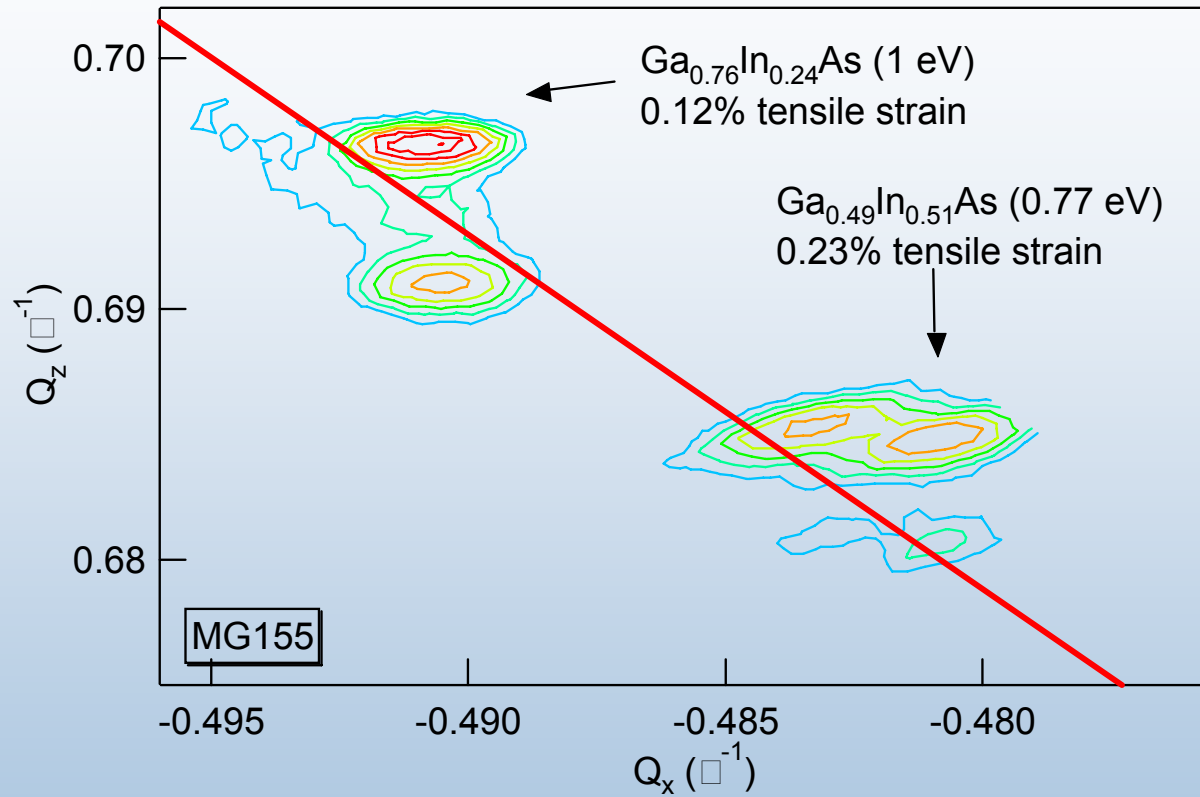


not  
to  
scale

- Accounts for effect of lattice-mismatched growth
- Bypasses complexities of growth and especially of measurement of the other three junctions
- Tried bandgaps from 0.88–0.74 eV

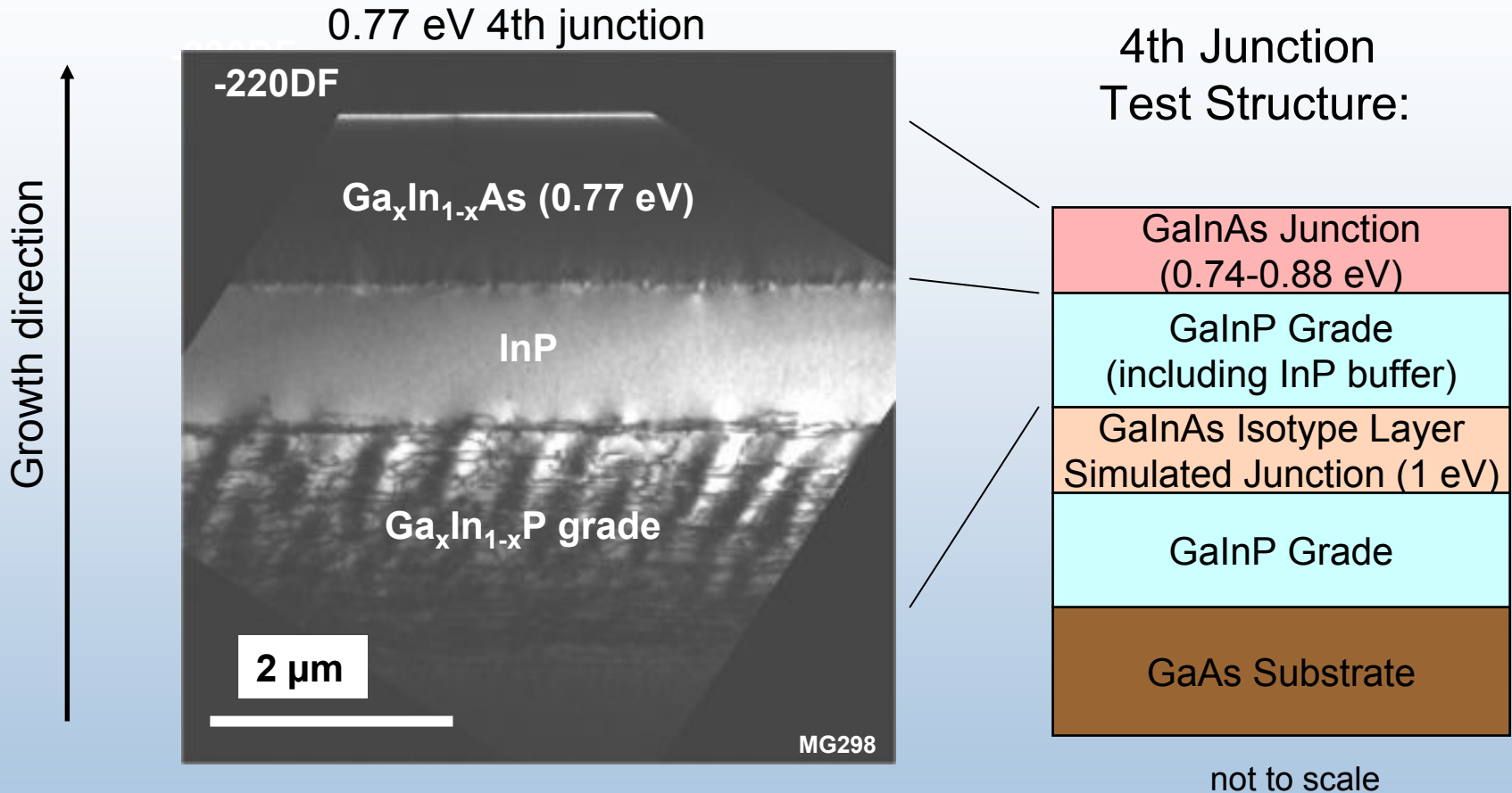


# X-ray Characterization of Strained Layers



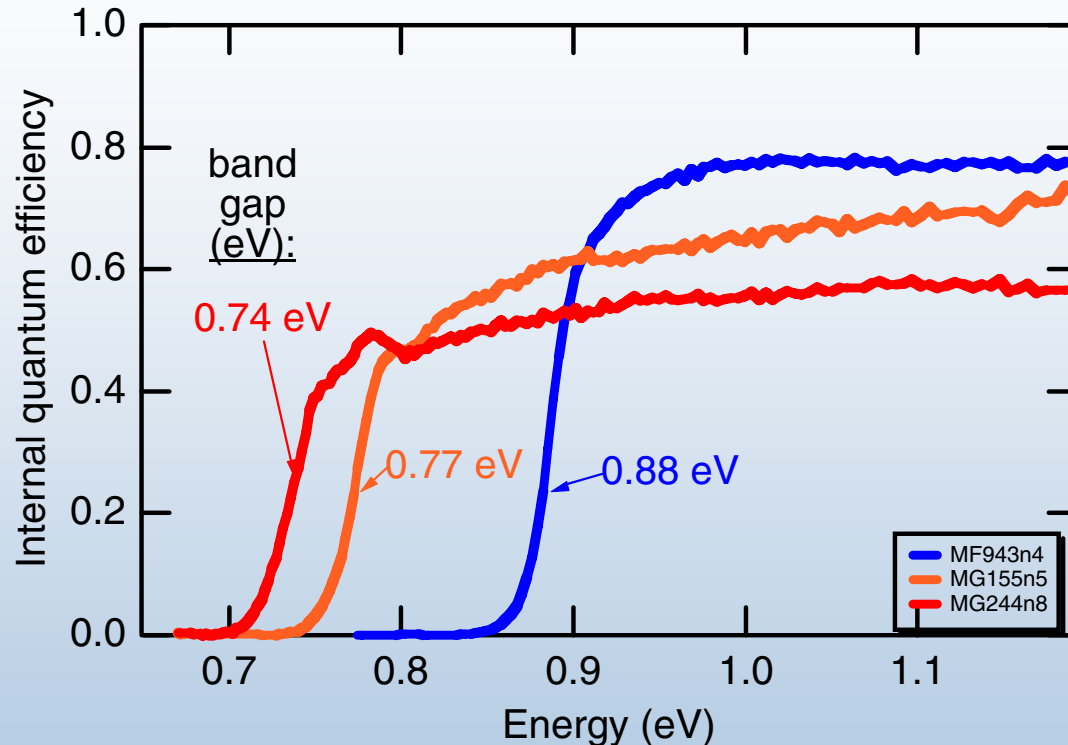
- XRD analysis critical to getting the compositions correct

# TEM Characterization: 4th Junction



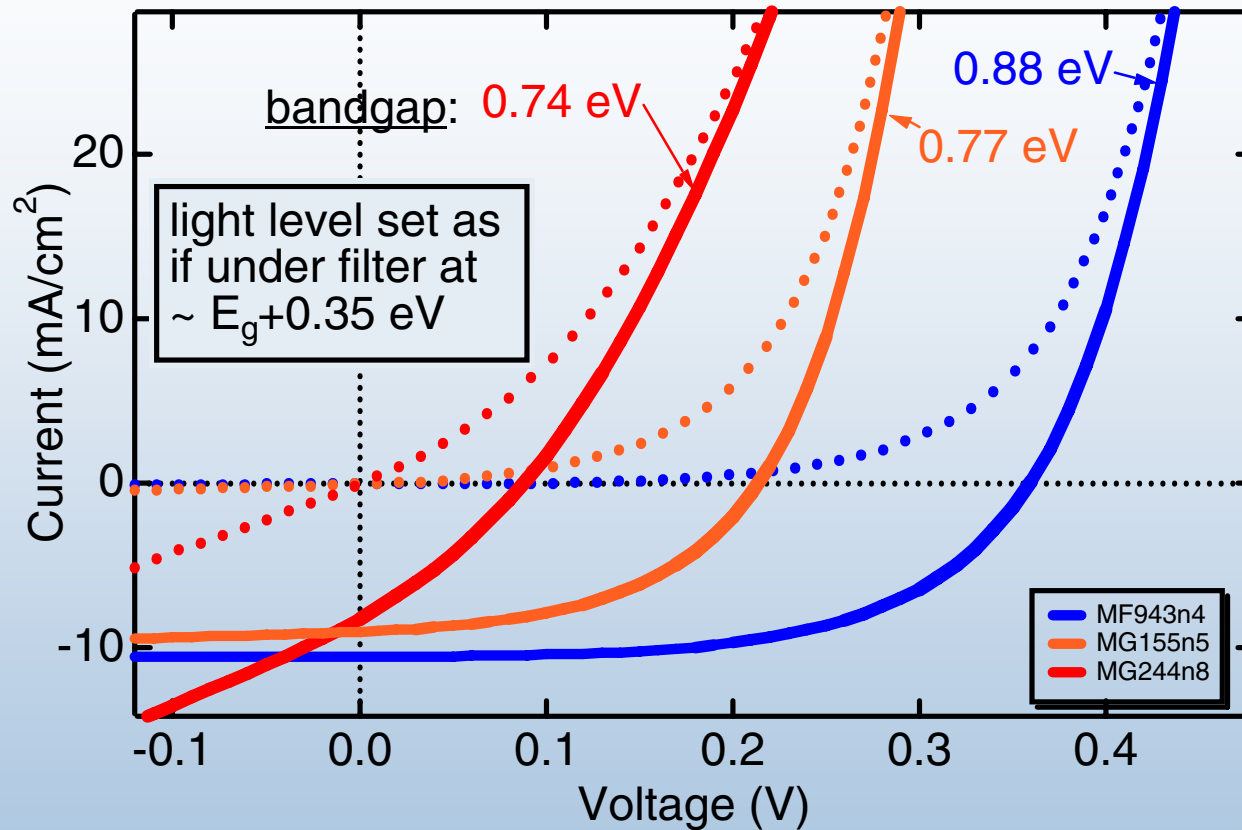
- Dislocations largely confined to grade

# Quantum Efficiency



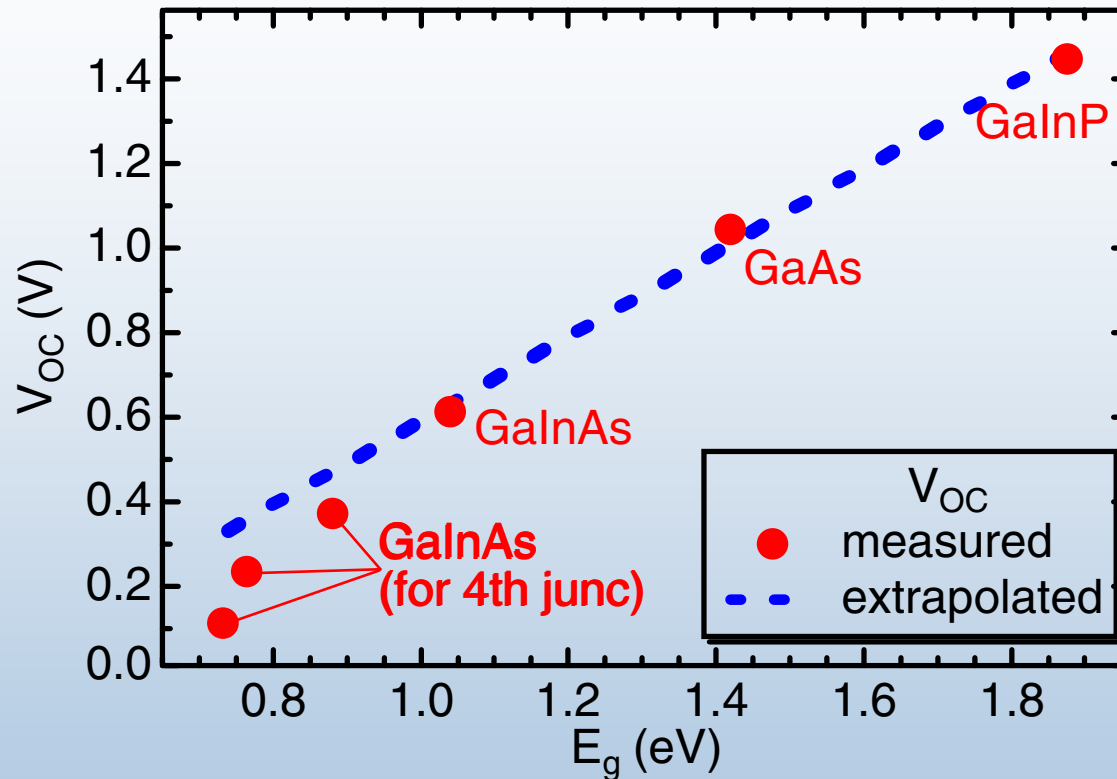
- QE degrades with increasing mismatch (decreasing  $E_g$ ) (note -- still room for improvement in these devices)
- QE of 0.88 eV device approaches performance required (note -- QE achieved without significant depletion region)

# Current-Voltage Characteristics



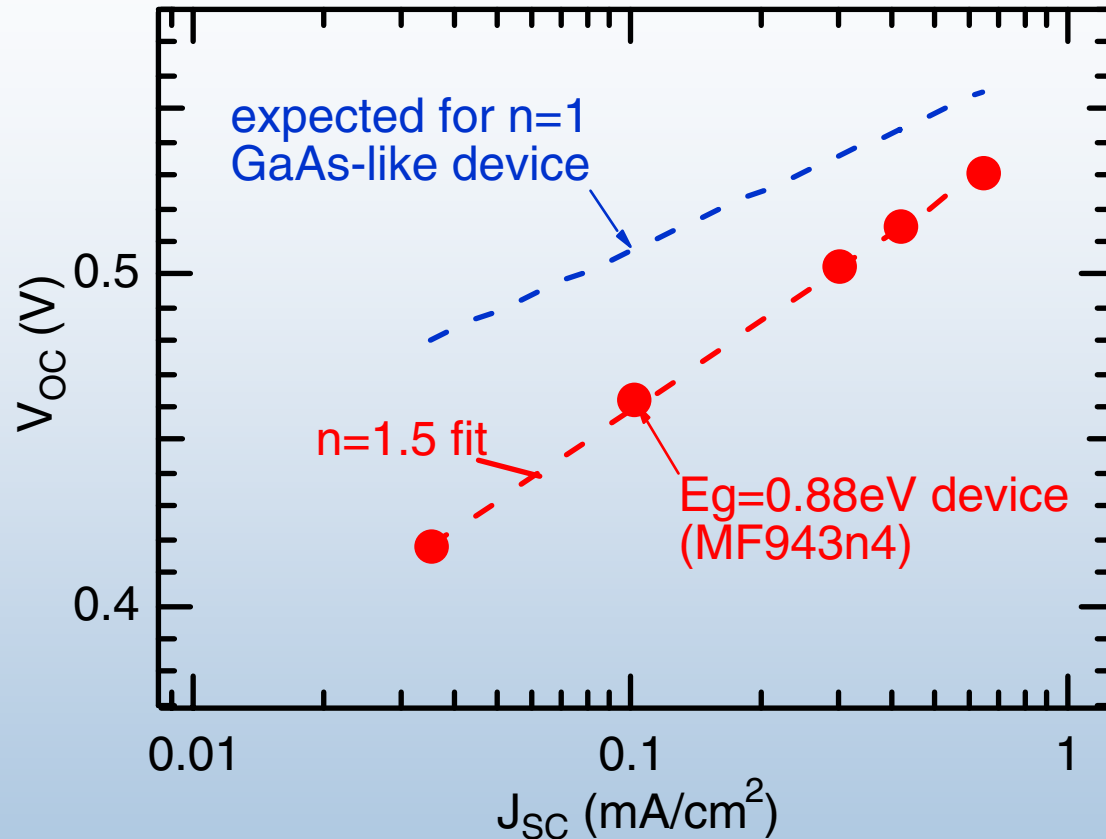
- $E_g = 0.74$  eV junction leaky, others good

# Dependence of $V_{OC}$ on Band Gap



- Lowest- $E_g$  junction degraded
- Higher- $E_g$  junctions better  
(and should get closer to GaAs-like with concentration)

# Improvement of Voc with Concentration

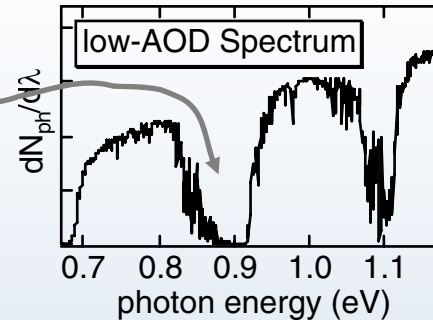
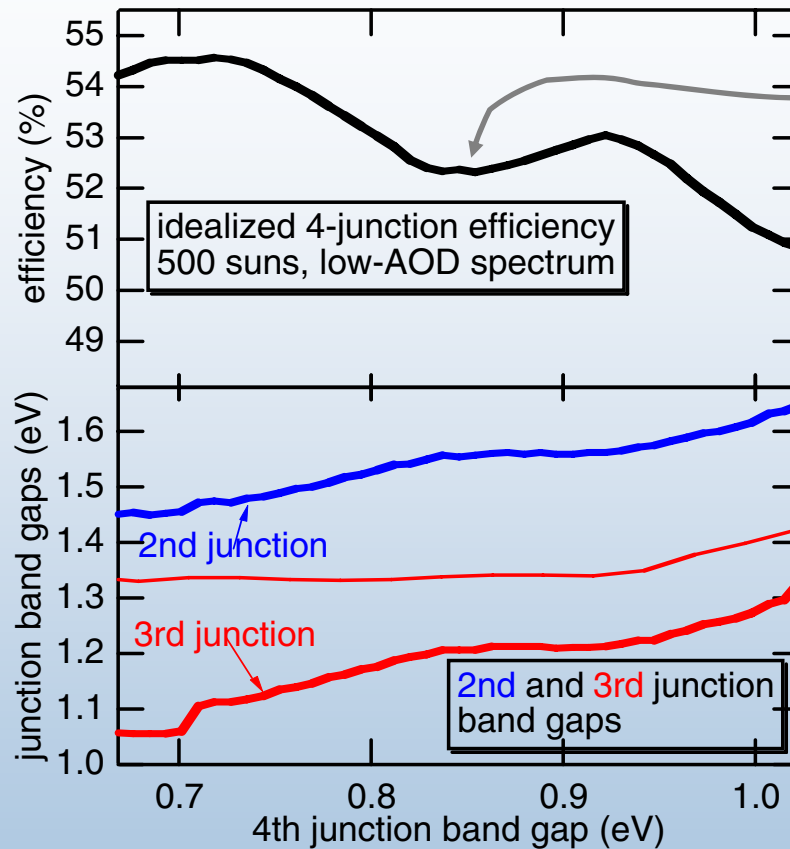


- Voc does get closer to GaAs-like with concentration, as expected

## 4th-Junction $E_g$ - is 0.7 eV Necessary?

- Good devices increasingly challenging as band gap decreases (i.e. mismatch increases)
- Can we get away with a higher 4th junction band gap?

# Allowing Band Gap to Vary



- Can raise 4th junction  $E_g$  from 0.7 to 0.9 eV and only lose 1.6% eff.
- Still 4% above GaInP/GaAs/1-eV 3j
- Real-world efficiency for the 0.9-eV option likely to be ~45%



# Device with 4th Junction $E_g=0.9$ eV

## Why consider this over the 0.7-eV option:

- High-quality 0.9-eV junction easier to make
- Efficiencies:
  - Only lose 1.6% efficiency compared to 0.7-eV option
  - Still 4% above the 1.85/1.41/1.0eV 3-junction efficiency
- Grade layers can be thinner:
  - Less time to grow
  - Less source material used
  - Less strain/wafer bowing

## Concerns:

- 1.6 eV junction needed: can it be as good as GaAs?
- Tunnel junctions need to be demonstrated

# Outlook

- A cornucopia of promising approaches to next-generation high efficiencies
  - may be places for more than one, in different cost-performance niches
- Inverted multijunction approach
  - Extending to 4 junctions likely to boost efficiencies by several %, to ~45%
  - 4-junction structure likely to use an 0.9-eV bottom junction

# A Golden Age for Multijunctions!

